

# 54ABT16245

## 16-Bit Transceiver with TRI-STATE® Outputs

### General Description

The 'ABT16245 contains sixteen non-inverting bidirectional buffers with TRI-STATE outputs and is intended for bus oriented applications. The device is byte controlled. Each byte has separate control inputs which can be shorted together for full 16-bit operation. The  $T/\bar{R}$  inputs determine the direction of data flow through the device. The  $\overline{OE}$  inputs disable both the A and B ports by placing them in a high impedance state.

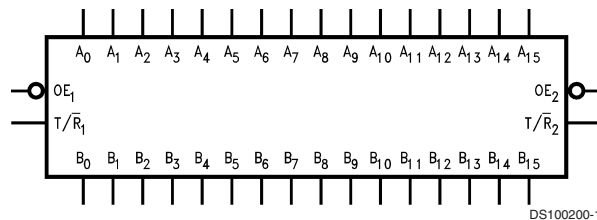
- Separate control logic for each byte
- 16-bit version of the 'ABT245
- A and B output sink capability of 48 mA, source capability of 24 mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Non-destructive hot insertion capability
- Standard Microcircuit Drawing (SMD) 5962-9317501

### Features

- Bidirectional non-inverting buffers

Military	Package Number	Package Description
54ABT16245W-QML	WA48A	48-Lead Cerpack

### Logic Symbol



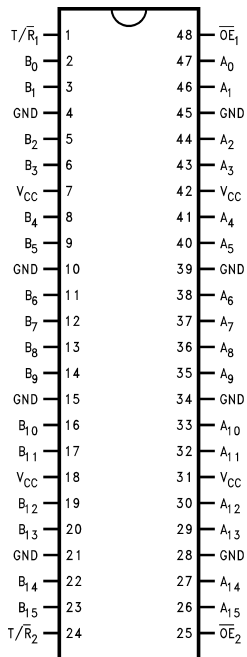
### Pin Description

Pin Names	Description
$\overline{OE}_n$	Output Enable Input (Active Low)
$T/\bar{R}_n$	Transmit/Receive Input
$A_0-A_{15}$	Side A Inputs/Outputs
$B_0-B_{15}$	Side B Inputs/Outputs

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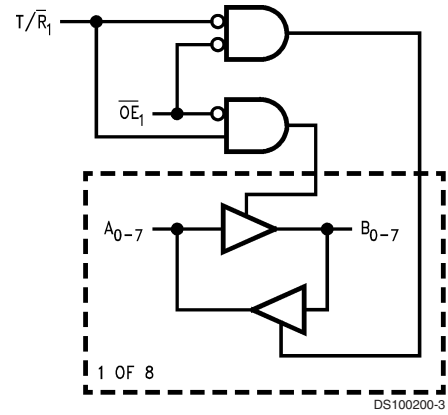
## Connection Diagram

Pin Assignment for Cerpac

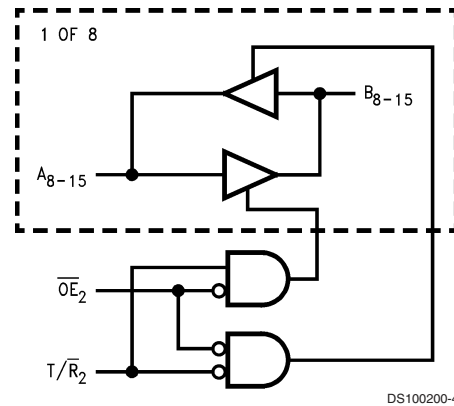


DS100200-2

## Logic Diagrams



DS100200-3



DS100200-4

## Functional Description

The 'ABT16245 contains sixteen non-inverting bidirectional buffers with TRI-STATE outputs. The device is byte controlled with each byte functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation.

Inputs		Outputs
$\overline{OE}_1$	$T/\overline{R}_1$	
L	L	Bus $B_0-B_7$ Data to Bus $A_0-A_7$
L	H	Bus $A_0-A_7$ Data to Bus $B_0-B_7$
H	X	HIGH-Z State on $A_0-A_7, B_0-B_7$

Inputs		Outputs
$\overline{OE}_2$	$T/\overline{R}_2$	
L	L	Bus $B_8-B_{15}$ Data to Bus $A_8-A_{15}$
L	H	Bus $A_8-A_{15}$ Data to Bus $B_8-B_{15}$
H	X	HIGH-Z State on $A_8-A_{15}, B_8-B_{15}$

H = High Voltage Level  
 L = Low Voltage Level  
 X = Immaterial  
 Z = High Impedance

**Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	
Ceramic	-55°C to +175°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Any Output in the Disabled or Power-off State	-0.5V to 5.5V
in the HIGH State	-0.5V to V <sub>CC</sub>

Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)
DC Latchup Source Current	-500 mA
Over Voltage Latchup (I/O)	10V

**Recommended Operating Conditions**

Free Air Ambient Temperature	
Military	-55°C to +125°C
Supply Voltage	
Military	+4.5V to +5.5V
Minimum Input Edge Rate	(ΔV/Δt)
Data Input	50 mV/ns
Enable Input	20 mV/ns

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**DC Electrical Characteristics**

Symbol	Parameter	ABT16245			Units	V <sub>CC</sub>	Conditions
		Min	Typ	Max			
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized HIGH Signal
V <sub>IL</sub>	Input LOW Voltage	0.8			V		Recognized LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage	-1.2			V	Min	I <sub>IN</sub> = -18 mA ( $\overline{OE}_n, T/\overline{R}_n$ )
V <sub>OH</sub>	Output HIGH Voltage	54ABT	2.5		V	Min	I <sub>OH</sub> = -3 mA (A <sub>n</sub> , B <sub>n</sub> )
		54ABT	2.0		V	Min	I <sub>OH</sub> = -24 mA (A <sub>n</sub> , B <sub>n</sub> )
V <sub>OL</sub>	Output LOW Voltage	54ABT	0.55		V	Min	I <sub>OL</sub> = 48 mA (A <sub>n</sub> , B <sub>n</sub> )
I <sub>IH</sub>	Input HIGH Current	5			μA	Max	V <sub>IN</sub> = 2.7V ( $\overline{OE}_n, T/\overline{R}_n$ ) (Note 3)
		5			μA	Max	V <sub>IN</sub> = V <sub>CC</sub> ( $\overline{OE}_n, T/\overline{R}_n$ )
I <sub>BVI</sub>	Input HIGH Current Breakdown Test	7			μA	Max	V <sub>IN</sub> = 7.0V ( $\overline{OE}_n, T/\overline{R}_n$ )
I <sub>BVIT</sub>	Input HIGH Current Breakdown Test (I/O)	100			μA	Max	V <sub>IN</sub> = 5.5V (A <sub>n</sub> , B <sub>n</sub> )
I <sub>IL</sub>	Input LOW Current	-5			μA	Max	V <sub>IN</sub> = 0.5V ( $\overline{OE}_n, T/\overline{R}_n$ ) (Note 3)
		-5			μA	Max	V <sub>IN</sub> = 0.0V ( $\overline{OE}_n, T/\overline{R}_n$ )
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA ( $\overline{OE}_n, T/\overline{R}_n$ ) All Other Pins Grounded
I <sub>IH</sub> + I <sub>OZH</sub>	Output Leakage Current	50			μA	0 – 5.5V	V <sub>OUT</sub> = 2.7V (A <sub>n</sub> , B <sub>n</sub> ); $\overline{OE} = 2.0V$
I <sub>IL</sub> + I <sub>OZL</sub>	Output Leakage Current	-50			μA	0 – 5.5V	V <sub>OUT</sub> = 0.5V (A <sub>n</sub> , B <sub>n</sub> ); $\overline{OE} = 2.0V$
I <sub>OS</sub>	Output Short-Circuit Current	-100	-275		mA	Max	V <sub>OUT</sub> = 0.0V (A <sub>n</sub> , B <sub>n</sub> )
I <sub>CEX</sub>	Output High Leakage Current	50			μA	Max	V <sub>OUT</sub> = V <sub>CC</sub> (A <sub>n</sub> , B <sub>n</sub> )
I <sub>ZZ</sub>	Bus Drainage Test	100			μA	0.0	V <sub>OUT</sub> = 5.50V (A <sub>n</sub> , B <sub>n</sub> ); All Others GND
I <sub>CCH</sub>	Power Supply Current	100			μA	Max	All Outputs HIGH
I <sub>CCL</sub>	Power Supply Current	60			mA	Max	All Outputs LOW
I <sub>CCZ</sub>	Power Supply Current	100			μA	Max	$\overline{OE}_n = V_{CC}, T/\overline{R}_n = GND$ or V <sub>CC</sub> All others at V <sub>CC</sub> or GND
I <sub>CCT</sub>	Additional I <sub>CC</sub> /Input	Outputs Enabled	2.5		mA	Max	V <sub>I</sub> = V <sub>CC</sub> - 2.1V
		Outputs TRI-STATE	2.5		mA		$\overline{OE}_n, T/\overline{R}_n, V_I = V_{CC} - 2.1V$
		Outputs TRI-STATE	50		μA		Data Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V All others at V <sub>CC</sub> or GND

## DC Electrical Characteristics (Continued)

Symbol	Parameter	ABT16245			Units	$V_{CC}$	Conditions
		Min	Typ	Max			
$I_{CCD}$	Dynamic $I_{CC}$ No Load		0.1		mA/ MHz	Max	Outputs Open $\overline{OE}_n = GND$ , $T/\overline{R}_n = GND$ or $V_{CC}$ One Bit Toggling, 50% Duty Cycle

**Note 3:** Guaranteed, but not tested.

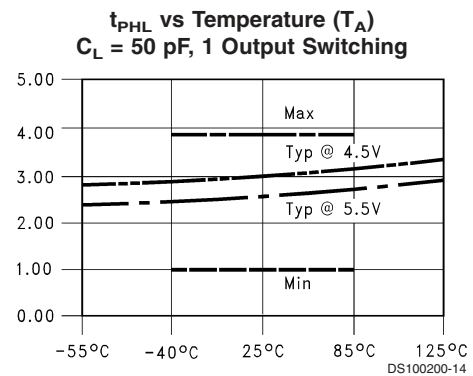
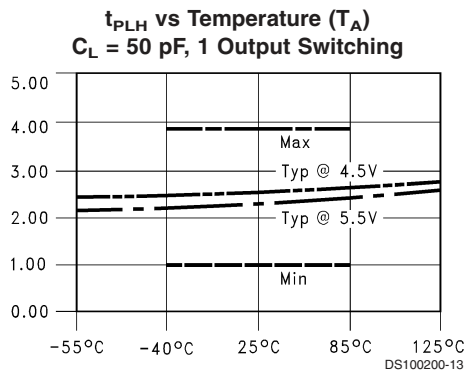
## AC Electrical Characteristics

Symbol	Parameter	54ABT		Units	Fig. No.
		$T_A =$ $-55^\circ\text{C to }+125^\circ\text{C}$ $V_{CC} = 4.5\text{V}-5.5\text{V}$ $C_L = 50\text{ pF}$			
		Min	Max		
$t_{PLH}$ $t_{PHL}$	Propagation Delay Data to Outputs	0.5	4.5	ns	Figure 5
		0.5	5.2		
$t_{PZH}$ $t_{PZL}$	Output Enable Time	0.8	6.4	ns	Figure 4
		0.9	6.9		
$t_{PHZ}$ $t_{PLZ}$	Output Disable Time	1.3	6.9	ns	Figure 4
		1.0	6.9		

## Capacitance

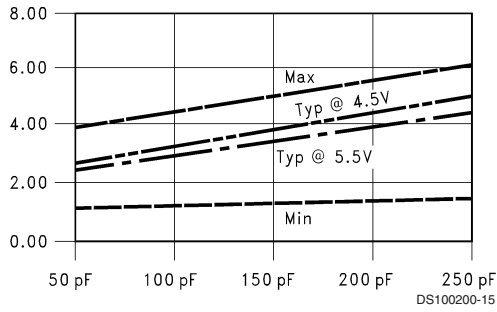
Symbol	Parameter	Typ	Units	Conditions, $T_A = 25^\circ\text{C}$
$C_{IN}$	Input Capacitance	5	pF	$V_{CC} = 0.0\text{V}$ ( $\overline{OE}_n$ , $T/\overline{R}_n$ )
$C_{I/O}$ (Note 4)	Output Capacitance	11	pF	$V_{CC} = 5.0\text{V}$ ( $A_n$ , $B_n$ )

**Note 4:**  $C_{I/O}$  is measured at frequency  $f = 1\text{ MHz}$ , per MIL-STD-883B, Method 3012.

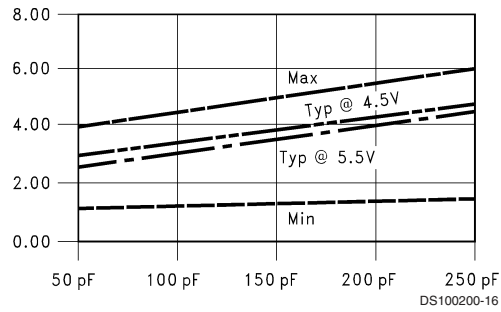


Capacitance (Continued)

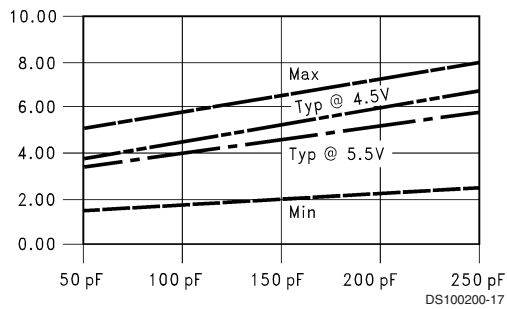
**$t_{PLH}$  vs Load Capacitance**  
1 Output Switching,  $T_A = 25^\circ\text{C}$



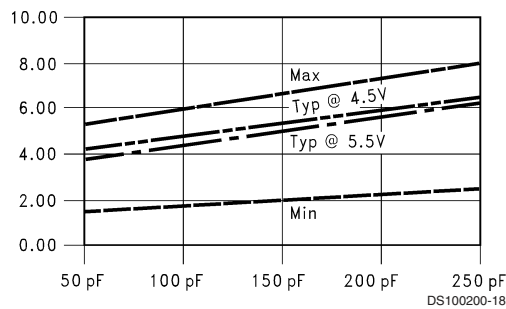
**$t_{PHL}$  vs Load Capacitance**  
1 Output Switching,  $T_A = 25^\circ\text{C}$



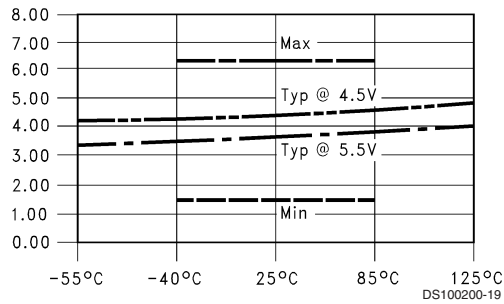
**$t_{PLH}$  vs Load Capacitance**  
16 Outputs Switching,  $T_A = 25^\circ\text{C}$



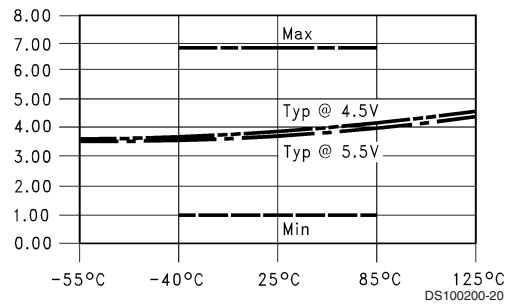
**$t_{PHL}$  vs Load Capacitance**  
16 Outputs Switching,  $T_A = 25^\circ\text{C}$



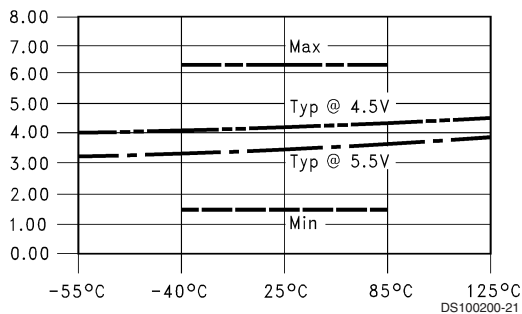
**$t_{PZL}$  vs Temperature ( $T_A$ )**  
 $C_L = 50\text{ pF}$ , 1 Output Switching



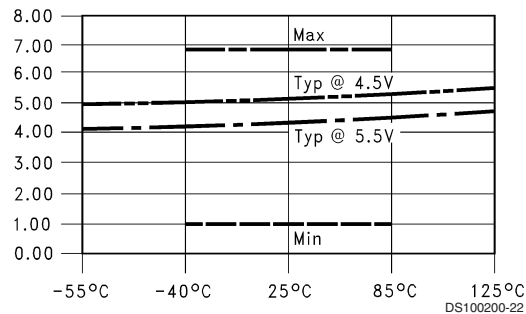
**$t_{PLZ}$  vs Temperature ( $T_A$ )**  
 $C_L = 50\text{ pF}$ , 1 Output Switching



**$t_{PZH}$  vs Temperature ( $T_A$ )**  
 $C_L = 50\text{ pF}$ , 1 Output Switching



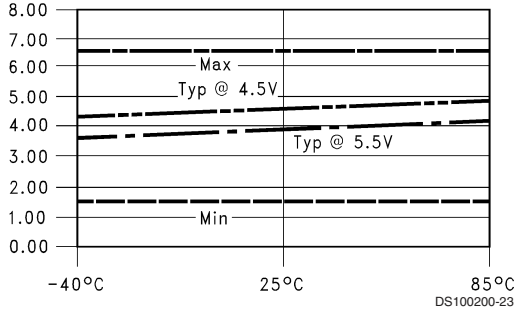
**$t_{PHZ}$  vs Temperature ( $T_A$ )**  
 $C_L = 50\text{ pF}$ , 1 Output Switching



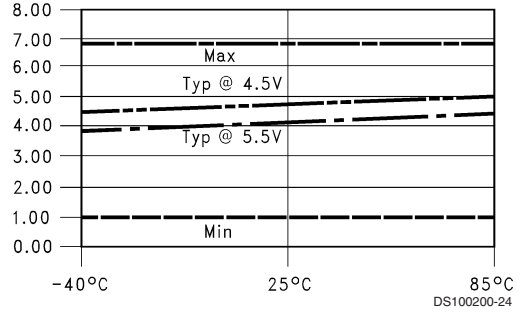
Dashed lines represent design characteristics; for specified guarantees, refer to AC Characteristics Table.

**Capacitance** (Continued)

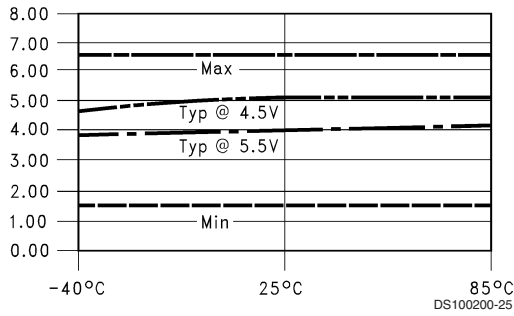
**$t_{PZH}$  vs Temperature ( $T_A$ )**  
 $C_L = 50$  pF, 16 Outputs Switching



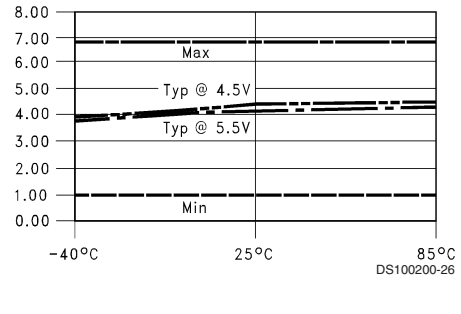
**$t_{PHZ}$  vs Temperature ( $T_A$ )**  
 $C_L = 50$  pF, 16 Outputs Switching



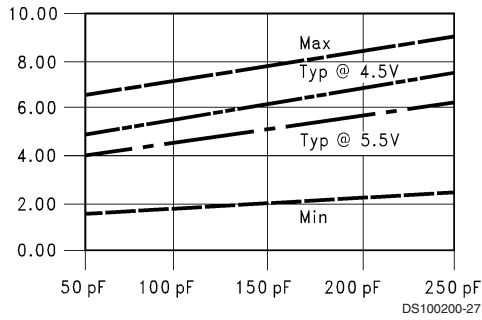
**$t_{PZL}$  vs Temperature ( $T_A$ )**  
 $C_L = 50$  pF, 16 Outputs Switching



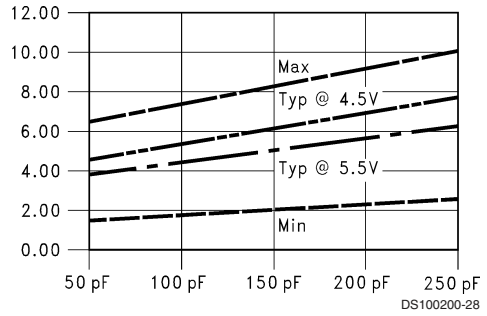
**$t_{PLZ}$  vs Temperature ( $T_A$ )**  
 $C_L = 50$  pF, 16 Outputs Switching



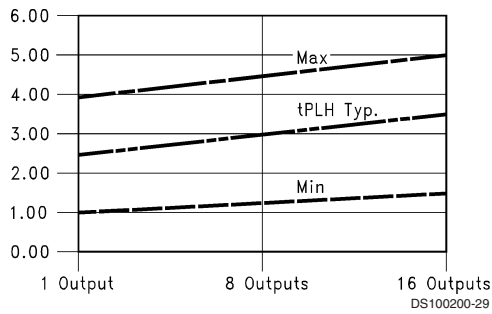
**$t_{PZL}$  vs Load Capacitance**  
 16 Outputs Switching  $T_A = 25^\circ\text{C}$



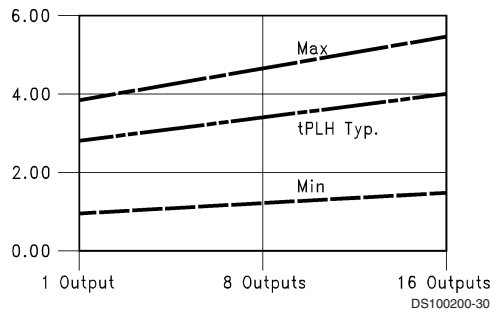
**$t_{PZH}$  vs Load Capacitance**  
 16 Outputs Switching  $T_A = 25^\circ\text{C}$



**$t_{PLH}$  vs Number Output Switching**  
 $V_{CC} = 5.0\text{V}$ ,  $T_A = 25^\circ\text{C}$ ,  $C_L = 50$  pF



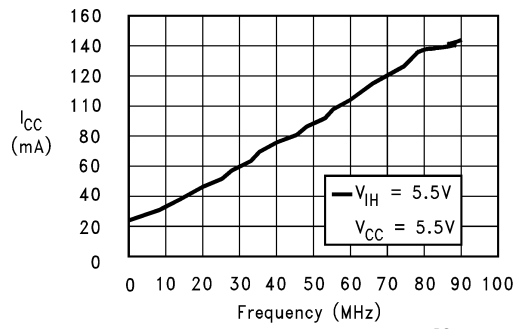
**$t_{PHL}$  vs Number Output Switching**  
 $V_{CC} = 5.0\text{V}$ ,  $T_A = 25^\circ\text{C}$ ,  $C_L = 50$  pF



Dashed lines represent design characteristics; for specified guarantees, refer to AC Characteristics Table.

**Capacitance** (Continued)

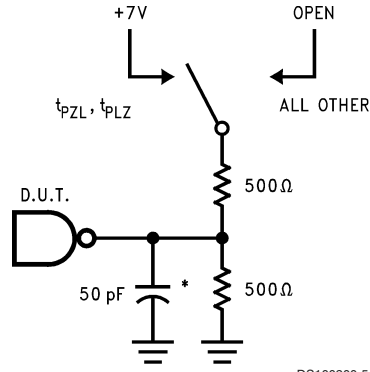
**$I_{CC}$  vs Frequency**  
**Average,  $T_A = 25^\circ\text{C}$ ,  $V_{CC} = 5.5\text{V}$**   
**All Outputs Unloaded/Unterminated;**  
**16 Outputs Switching In-Phase at 50% Duty Cycle**



DS100200-31

Dashed lines represent design characteristics; for specified guarantees, refer to AC Characteristics Table.

# AC Loading



\*Includes jig and probe capacitance

FIGURE 1. Standard AC Test Load

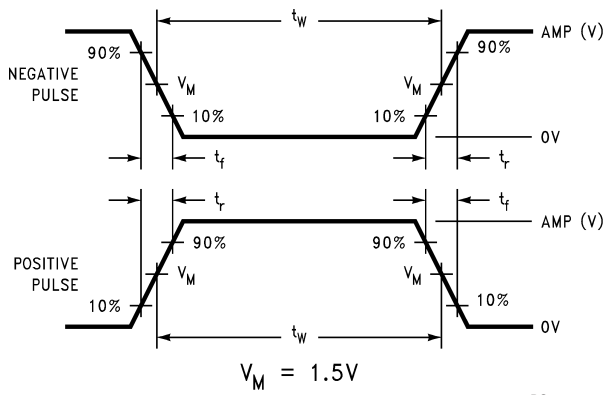


FIGURE 2. Input Pulse Requirements

Amplitude	Rep. Rate	$t_w$	$t_r$	$t_f$
3.0V	1 MHz	500 ns	2.5 ns	2.5 ns

FIGURE 3. Test Input Signal Requirements

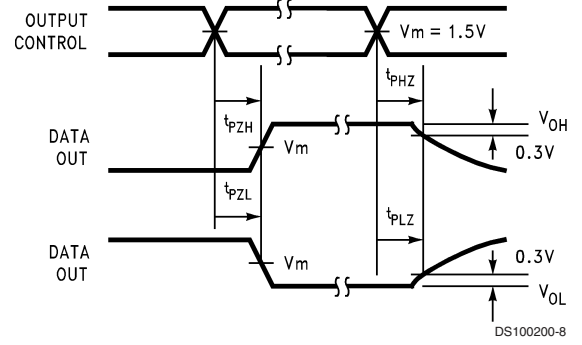


FIGURE 4. TRI-STATE Output HIGH and LOW Enable and Disable Times

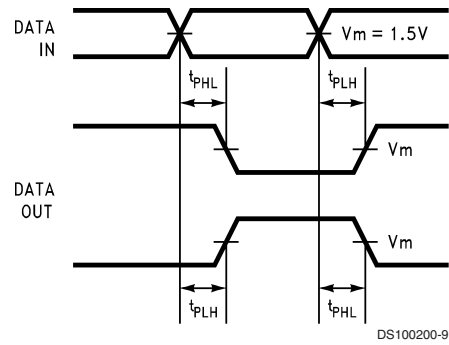
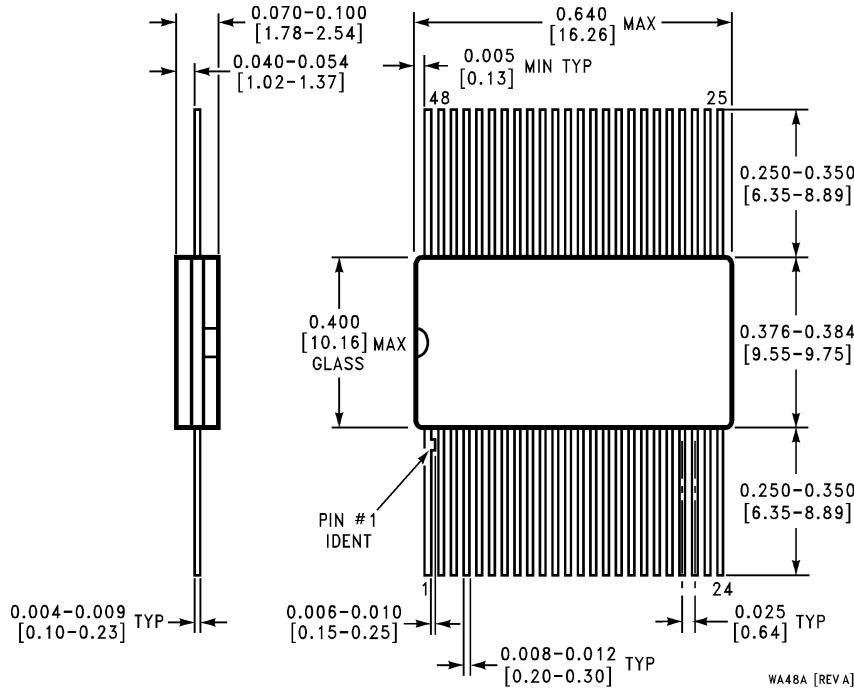


FIGURE 5. Propagation Delay Waveforms for Inverting and Non-Inverting Functions

**Physical Dimensions** inches (millimeters) unless otherwise noted



**48-Lead Cerpack**  
**NS Package Number WA48A**

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